



Material Content Data Sheet



Sales Product Name	IPU60R1K4C6			Issued		29. September 2015		
MA#	MA001348748							
Package	PG-TO251-3-341			Weight*		387.64 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.624	0.42	0.42	4190	4190
leadframe	non noble metal	iron	7439-89-6	0.248	0.06		641	
	inorganic material	phosphorus	7723-14-0	0.075	0.02		192	
	non noble metal	copper	7440-50-8	248.124	64.03	64.11	640080	640913
wire	non noble metal	aluminium	7429-90-5	0.439	0.11	0.11	1134	1134
encapsulation	organic material	carbon black	1333-86-4	0.393	0.10		1013	
	plastics	epoxy resin	-	11.916	3.07		30739	
	inorganic material	silicondioxide	60676-86-0	118.636	30.60	33.77	306044	337796
leadfinish	non noble metal	tin	7440-31-5	3.787	0.98	0.98	9769	9769
plating	non noble metal	nickel	7440-02-0	0.515	0.13	0.13	1329	1329
solder	noble metal	silver	7440-22-4	0.047	0.01		122	
	non noble metal	tin	7440-31-5	0.038	0.01		97	
	non noble metal	lead	7439-92-1	1.802	0.46	0.48	4650	4869
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com